

**IN THE CLAIMS**

This is a complete and current listing of the claims, marked with status identifiers in parentheses. The following listing of claims will replace all prior versions and listings of claims in the application.

1. (Currently Amended) A semiconductor relay, comprising:  
~~\_\_\_\_\_ having an essentially cuboid housing (20) which~~  
~~has~~including an attachment face (3) as well as and including, as  
connecting faces, four side surfaces (4, 5, 6, 7), which are  
arranged at right angles to the attachment face, and a  
front face (8) which is opposite the attachment face (3), as  
connecting faces (4, 5, 6, 7, 8),; and  
~~characterized in that~~ at least one electrical connection  
element (11, 12) and at least one mechanical connection  
element, (19, 24) are provided on a number of the connecting  
faces, (4, 5, 6, 7, 8) overall for connection of a functional  
module (1) which can be connectedconnectable to the housing  
~~(20).~~

2. (Currently Amended) The semiconductor relay as claimed in  
claim 1, wherein the  
~~characterized by a functional module (1) which is connected to~~  
~~two connecting faces (4, 5, 6, 7, 8).~~

3. (Currently Amended) The semiconductor relay as claimed in claim ~~1 or 2~~, wherein  
~~characterized in that the functional module (1) is provided for~~  
load circuit monitoring.

4. (Currently Amended) The semiconductor relay as claimed in ~~one of claims 1 to 3~~, wherein  
~~characterized in that the functional module (1) is provided for~~  
power control in the load circuit.

5. (Currently Amended) The semiconductor relay as claimed in ~~one of claims 1 to 4~~, wherein  
~~characterized in that the functional module (1) can be driven~~  
is drivable by means use of an analogue signal.

6. (Currently Amended) The semiconductor relay as claimed in ~~one of claims 1 to 5~~, wherein  
~~characterized in that the functional module (1) is provided for~~  
current measurement.

7. (Currently Amended) The semiconductor relay as claimed in ~~one of claims 1 to 6~~, wherein  
~~characterized in that the functional module (1) is provided for~~  
analogue/digital signal conversion.

8. (Currently Amended) The semiconductor relay as claimed in ~~one of claims 1 to 7~~, wherein  
~~characterized in that the functional module (1) can be connected~~  
is connectable to the housing (20) ~~without the use of any~~  
tools.

9. (Currently Amended) The semiconductor relay as claimed in  
claim 8, wherein  
~~characterized in that the functional module (1) can be snapped~~  
is snapable onto the housing ~~(20)~~.

10. (Currently Amended) The semiconductor relay as claimed in  
~~one of claims 1 to 9~~, wherein  
~~characterized in that a plurality of functional modules (1) can~~  
~~be connected~~ are connectable to the housing ~~(20)~~.

11. (Currently Amended) The semiconductor relay as claimed in  
~~one of claims 1 to 10~~, wherein  
~~characterized in that the functional module (1) includes~~has a  
base face (16) ~~which is aligned with the attachment face (3) of~~  
the housing ~~(20)~~.

12. (Currently Amended) The semiconductor relay as claimed in  
~~one of claims 1 to 11~~, wherein

~~characterized in that~~ the functional module ~~(1)~~ has two attachment limbs ~~(25)~~, ~~which are~~ arranged on both sides of an opening ~~(26)~~ in the housing ~~(20)~~ and each aligned parallel to one side surface ~~(4, 5, 6, 7)~~.

13. (New) The semiconductor relay as claimed in claim 2, wherein the functional module is provided for load circuit monitoring.

14. (New) The semiconductor relay as claimed in claim 2, wherein the functional module is provided for power control in the load circuit.